

WHAT IS CLAIMED IS:

1. An electronic component module comprising:
a circuit substrate having circuit components mounted thereon; and
a recess provided in the top surface of said circuit substrate, said recess including a plurality of regions where the thicknesses of bottom plates of said recess differ from one another, and said recess including at least one portion of the circuit components mounted on said circuit substrate.
2. An electronic component module as claimed in claim 1, wherein the top surface of each of the circuit components mounted in said recess is substantially flush with the top surface of said circuit substrate.
3. An electronic component module as claimed in claim 1, wherein said circuit components define a quartz vibrator package.
4. An electronic component module as claimed in claim 1, wherein said circuit substrate is a ceramic circuit substrate.

5. An electronic component module as claimed in claim 1, wherein said circuit substrate is defined by a ceramic multi-layer substrate.

6. An electronic component module as claimed in claim 1, wherein said circuit substrate includes a wall surrounding said recess, and connection electrodes are provided at four corners on a top surface of the wall.

7. An electronic component module as claimed in claim 6, wherein said connection electrodes are arranged to define a connection with the circuit components.

8. An electronic component module comprising:
a circuit substrate; and
a plurality of recesses, each being having an insular shape on the top surface of the circuit substrate, and each accommodating a circuit component.

9. An electronic component module as claimed in claim 8, wherein at least one portion of said plurality of recesses has a different depth from other of said plurality of recesses.

10. An electronic component module as claimed in claim

8, wherein the top surface of each of the circuit components mounted in said recess is substantially flush with the top surface of said circuit substrate.

11. An electronic component module as claimed in claim 8, wherein said circuit components define a quartz vibrator package.

12. An electronic component module as claimed in claim 8, wherein said circuit substrate is a ceramic circuit substrate.

13. An electronic component module as claimed in claim 8, wherein said circuit substrate includes a wall surrounding said recess, and connection electrodes are provided at four corners on a top surface of the wall.

14. An electronic component module as claimed in claim 13, wherein said connection electrodes are arranged to be connected with the circuit components.

15. A piezoelectric oscillator comprising:
at least one oscillation circuit including an
electronic component module as claimed in claim 1; and
a vibrator package accommodating a piezoelectric

member, said vibrator package being stacked on said electronic component module, and said vibrator package being integrated with said electronic component module.

16. A piezoelectric oscillator according to claim 15, wherein said vibrator package includes a case having an open top surface, said electronic component module being supported at both end portions thereof by said case.

17. A piezoelectric oscillator according to claim 16, further comprising a shielding plate, wherein the entire top surface of the case is covered by the shielding plate, such that said electronic component module is hermetically sealed in said vibration package defined by the case and the shielding plate.

18. A piezoelectric oscillator comprising:
at least one oscillation circuit including an electronic component module as claimed in claim 8; and
a vibrator package accommodating a piezoelectric member, said vibrator package being stacked on said electronic component module, and said vibrator package being integrated with said electronic component module.

19. A piezoelectric oscillator according to claim 18,

20. A piezoelectric oscillator according to claim 19, further comprising a shielding plate, wherein the entire top surface of the case is covered by the shielding plate, such that said electronic component module is hermetically sealed in said vibration package defined by the case and the shielding plate.